

ABSTRACT

The present invention relates to a substrate processing apparatus and a substrate processing method for suppressing cracking and chipping of a laminated substrate manufactured by bonding substrates, and more particularly to a technique of applying a
5 filler to a gap formed between edge portions of the substrates constituting the laminated substrate. The method includes: applying the filler (F) to a gap between an edge portion (E1) of the first substrate (W1) and an edge portion (E2) of the second substrate (W2); curing the applied filler (F); generating, by an infrared imaging device (5), an image of an edge portion of the laminated substrate (Ws) to which the filler (F) is applied; and
10 determining a filling state of the filler (F) applied to the gap between the edge portion (E1) of the first substrate (W1) and the edge portion (E2) of the second substrate (W2) based on the image.

Figure 3